

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

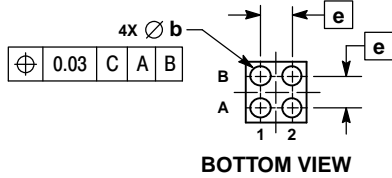
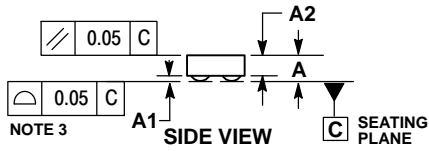
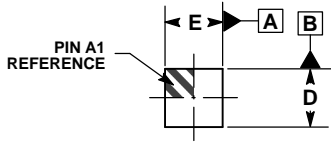
ON Semiconductor®



SCALE 4:1

WLCSP4, 0.64x0.64  
CASE 567JZ  
ISSUE A

DATE 03 AUG 2016

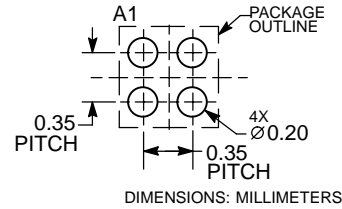


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	---	---	0.33
A1	0.04	0.06	0.08
A2	0.23 REF		
b	0.195	0.210	0.225
D	0.610	0.640	0.670
E	0.610	0.640	0.670
e	0.35 BSC		

RECOMMENDED  
SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WLCSP4, 0.64X0.64	PAGE 1 OF 2

